

Title (en)

Electroplating plant, use of electrode and support system therefor and electroplating process

Title (de)

Elektroplattierungsanlage, Verwendung von Elektrode und Gegenhalter dafür und Elektroplattierungsverfahren

Title (fr)

Installation d'électrodéposition, utilisation d'électrode et organe d'appui pour cette installation et procédé d'électrodéposition

Publication

EP 0922791 B1 20030305 (FR)

Application

EP 98402805 A 19981113

Priority

FR 9715179 A 19971203

Abstract (en)

[origin: US6129820A] An electroplating installation for coating the conducting surface of a part. The installation includes electrodes submerged in a bath. The electrodes rest on a support device that serves as a support and a current supply. The electrodes and the support device form an interface defining a plurality of grooves opening into the bath. The grooves may be formed in the electrodes, in the support device, or in both the electrodes and the support device.

IPC 1-7

C25D 17/00; **C25D 7/06**

IPC 8 full level

C25D 17/10 (2006.01); **C25D 7/06** (2006.01); **C25D 17/00** (2006.01)

CPC (source: EP US)

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Designated contracting state (EPC)

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DOCDB simple family (publication)

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US 20454598 A 19981203; AT 98402805 T 19981113; DE 69811836 T 19981113; EP 98402805 A 19981113; ES 98402805 T 19981113; FR 9715179 A 19971203; JP 34443498 A 19981203; US 63702600 A 20000814